

05/02/2013

M204-26-13



EET



To: Commissioner of Patents and

103657817

original document or copy:

## 1. Name of conveying party(ies):

Yuhang Ren, Zhi Huang, Paifeng Luo,  
Kai ShumAdditional names? ☐ Yes ☒ No

## 2. Name and address of receiving party(ies):

Name: Sun Harmonics Ltd, a Chinese corporation hereafter  
called the "Assignee," having place of business at: 1500  
Wenyi Rd. Building #3, Technology Incubation Center,  
Hangzhou, Zhejiang, China, 311121

## 3. Nature of conveyance:

☒ Assignment ☐ Merger  
☐ Security Agreement ☐ Change of Name  
☐ OtherAdditional names & addresses attached? ☐ Yes ☒ No

Execution Date: April 23, April 24, 2013

## 4. Application number(s) or patent number(s):

Attorney Docket No.: SUNHA.P2

If this document is being filed together with a new application, execution date of application is: April 25, 2013

Additional numbers attached? ☐ Yes ☒ No5. Name and address of party to whom correspondence  
should be mailed: Address associated with Customer  
No.: 28752

Name: \_\_\_\_\_

Internal Address: \_\_\_\_\_

Street Address: \_\_\_\_\_

City: \_\_\_\_\_ State: \_\_\_\_\_ ZIP: \_\_\_\_\_

## 6. Total number of applications and patents involved: 1

7. Total fee (37 CFR 3.41): \$40.00

☐ Enclosed☒ Authorized charge to Deposit Acct No 10-0100  
(Lackebach Siegel LLP)8. ☒ Charge any additional fees in connection with  
this submission to our Deposit Account No. 10-0100

DO NOT USE THIS SPACE

## 9. Statement and signature.

To the best of my knowledge and belief, the foregoing information is true and correct and any attached copy is  
a true copy of the original document.

Myron Greenspan, Reg. No. 25,680

Name of Person Signing

Signature

April 25, 2013

Total number of pages including cover sheet, attachments, and document: 5 01 FC:8021 40.00 DA

05/02/2013 KNGUYEN1 0000 Date 100100

1871640

## Table of Contents (Selected Documents)

Date	Code	Pages	Source	PackageID	Annotation
04-26-2013	R3.73B	5	EFSW	US 1387164001P1	

**ASSIGNMENT**

In consideration of One Dollar (\$1.00), and other good and valuable consideration, the receipt of which is hereby acknowledged, the undersigned inventor:

Full Name of Sole or First Inventor	Yuhang Ren	
Residence	1500 Wenyi Rd. Building #3, Technology Incubation Center, Hangzhou, Zhejiang, China, 311121	Citizenship: China
Mailing Address	1500 Wenyi Rd. Building #3, Technology Incubation Center, Hangzhou, Zhejiang, China, 311121	

Full Name of Sole or Second Inventor	Zhi Huang	
Residence	1500 Wenyi Rd. Building #3, Technology Incubation Center, Hangzhou, Zhejiang, China, 311121	Citizenship: China
Mailing Address	1500 Wenyi Rd. Building #3, Technology Incubation Center, Hangzhou, Zhejiang, China, 311121	

Full Name of Sole or Third Inventor	Paifeng Luo	
Residence	1500 Wenyi Rd. Building #3, Technology Incubation Center, Hangzhou, Zhejiang, China, 311121	Citizenship: China
Mailing Address	1500 Wenyi Rd. Building #3, Technology Incubation Center, Hangzhou, Zhejiang, China, 311121	

Full Name of Sole or Fourth Inventor	Kai Shum	
Residence	1500 Wenyi Rd. Building #3, Technology Incubation Center, Hangzhou, Zhejiang, China, 311121	Citizenship: USA
Mailing Address	1500 Wenyi Rd. Building #3, Technology Incubation Center, Hangzhou, Zhejiang, China, 311121	

declare that they are citizens of the country indicated above and with residences as listed above,

Hereby sell, assign and transfer their undivided interest to Sun Harmonics Ltd, a Chinese corporation hereafter called the "Assignee," having place of business at: 1500 Wenyi Rd. Building #3, Technology Incubation Center, Hangzhou, Zhejiang, China, 311121

To his successors, assigns and legal representatives, the entire right, title and interest for the United States and worldwide, in and to any and all improvements which are described and claimed in the

X attached specification executed on \_\_\_\_\_

\_\_\_\_\_ specification Serial No. \_\_\_\_\_, filed  
\_\_\_\_\_ U.S. Letters Patent No. \_\_\_\_\_; issued \_\_\_\_\_

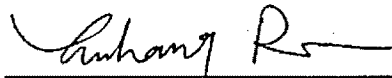
entitled: **METHOD OF FORMING AN I-III-VI<sub>2</sub> COMPOUND SEMICONDUCTOR THIN FILM OF CHALCOPYRITE STRUCTURE**

and in and to said application and all divisional, continuing, substitute, renewal, reissue, and all other applications for Letters Patent which have been or shall be filed in the United States or worldwide on any of said improvements; and in and to all original and reissued patents which have been or shall be issued in the United States or worldwide on said improvements;


Agree that said Assignee may apply for and receive Letters Patent for said improvements in its own name; and that, when requested, without charge to but at the expense of said Assignee, its successors, assigns and legal representatives, to carry out in good faith the intent and purpose of this assignment, the undersigned will execute all divisional, continuing, substitute, renewal, reissue, and all other patent applications on any and all said improvements; execute all rightful oaths, declarations, assignments, powers of attorney and other papers; communicate to said Assignee, its successors, assigns and representatives, all facts known to the undersigned relating to said improvements and the history thereof; and generally do everything possible which said Assignee, its successors, assigns or representatives shall consider desirable for aiding in securing and maintaining proper patent protection for said improvements and for vesting title to said improvements and all applications for patents and all patents on said improvements, in said Assignee, its successors, assigns and legal representatives; and

Covenant with said Assignee, its successors, assigns and legal representatives that no assignment, grant, mortgage, license or other agreement affecting the rights and property herein conveyed has been made to others by the undersigned, and that full right to convey the same as herein expressed is possessed by the undersigned.

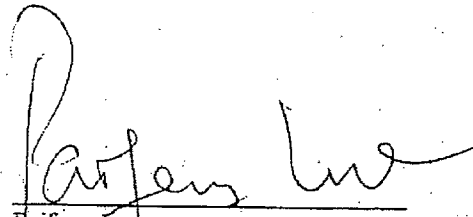
DATE 04/24/2013

  
Yuhang Ren

DATE 04/24/2013

  
Zhi Huang

DATE 4/23/13

  
\_\_\_\_\_  
Raifeng Luo

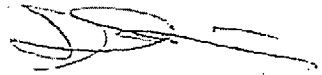
DATE \_\_\_\_\_

\_\_\_\_\_  
Kai Shum

DATE \_\_\_\_\_

\_\_\_\_\_  
Paifeng Luo

DATE 04-23-2013  
\_\_\_\_\_

  
\_\_\_\_\_  
Kai Shum